

CSP/Hybrid Socket

FEATURES

- Aries unique universal socketing system allows the socket to be easily configured for any package, on any pitch (or multiple pitch) from 0.2mm or greater, in any configuration, with little or no tooling charge or extra lead-time.
- For Test & Burn-In of CSP, μBGA, Bump-Array, QFN, QFP, MLF, DFN, SSOP, TSSOP, TSOP, SOP, SOIC, LGA, LCC, PLCC, TO and any SMT package style made, Also can be compatible with PGA packaged devices.
- Quick and easy **Probe Replacement System**: the complete set of probes can be removed and a new set (interposer) can be inserted quickly and easily. The old set can be returned to the factory for repair and sent back within one day.
- Socket lid nests device into socket for a reliable connection.
- ZIF style socket using Aries solderless, Au-plated pressure mount Spring-Probe.
- Special lid designs and/or materials can be quoted.
- Socket easily located, mounted & removed from PCB.
- Signal path during test only 0.077 [1.96].
- 4-point crown insures scrub on solder oxides consult factory for other available probe styles.
- The Au over Ni-plated compression Spring-Probes leave very small witness marks on the bottom surface of the device solder balls.



ORDERING INFORMATION

Consult Factory for P/N

CLEANING, HANDLING, MOUNTING & PROBE REPLACEMENT INFO

Need a Breakout Board? SPECIAL THERMAL REQUIREMENT WORKSHEET

GENERAL SPECIFICATIONS

- BODY MATERIAL: PEEK or TORLON
- 1dB BANDWIDTH: 1GHz (0.80mm pitch) (large probe)
- ESTIMATED CONTACT LIFE: 500,000 cycles
- COMPRESSION SPRING PROBES: heat-treated BeCu with 30μ [0.75μ] min. Au per MIL-G-45204 over 30µ [0.75µ] min. Ni per SAE AMS-QQ-N-290
- CONTACT FORCE: 6g per contact on 0.20-0.29mm pitch
 - : 15g per contact on 0.30-0.35mm pitch
 - : 16g per contact on 0.40-0.45mm pitch
 - : 25g per contact on 0.50-0.75mm pitch
 - : 25g per contact on 0.80mm pitch or larger
- OPERATING TEMPERATURE: -55°C [-67°] min. to 150°C [302°] max.
- SCREWS AND ALIGNMENT PINS: Stainless Steel
- INSERTS: Brass per QQ-B-626, Sn-plated
- OPERATING TEMPERATURE RANGE: -55°C to 150°C [-67° to 302°]

MOUNTING CONSIDERATIONS

- NOTE: Sockets must be handled with care when mounting or removing sockets to/from PCB
- TEST PCB MINIMUM DIAMETER "G": 0.025 [0.64] (large probe 0.80mm pitch and larger)

: 0.015 [0.38] (small probe 0.50-0.75mm pitch)

: 0.012 [0.31] (small probe 0.40-0.45mm pitch)

: 0.009 [0.23] (small probe 0.30-0.35mm pitch)

: 0.004 [0.10] (small probe 0.20-0.20mm pitch)

• TEST PCB DIAMETER SPRING PROBE PAD PLATING: 30µ [0.75µ] min. Au per MIL-G-45204 over 30µ [0.75µ] min. Ni per SEA AMS-QQ-N-290. Pad must be the same height as top surface of PCB. Please refer to the Custom Socket Drawing supplied by Aries after receipt of your order for your specific application.

Bristol, PA 19007-6810 USA

TEL (215) 781-9956 • FAX (215) 781-9845

A detailed device drawing must be sent to Aries to quote and design a socket.

See Data Sheet for...

CSP Sockets

23021 µBGA up to 6.5mm

23017 uBGA up to 13mm

23018 µBGA up to 27mm

23018-APP w/Adj Pressure Pad

23019 µBGA up to 40mm

23020 µBGA up to 55mm

23023 Optical Failure Analysis

RF Sockets

24013 RF up to 6.5mm

24008 RF up to 13mm

24009 RF up to 27mm

24009-APP w/Adj Pressure Pad

24011 RF up to 40mm

24012 RF up to 55mm

24010 RF Machined Socket

23022 Kelvin Test Socket

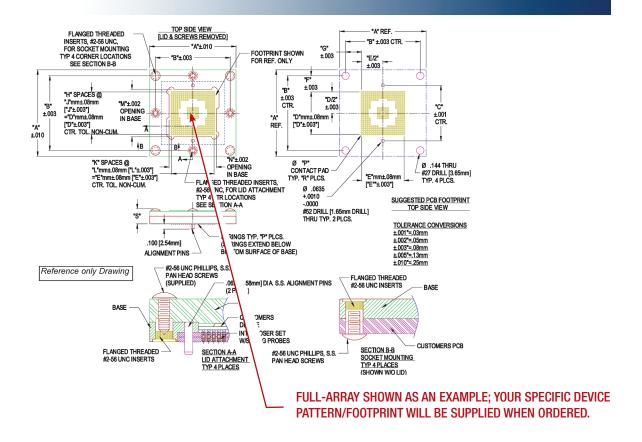


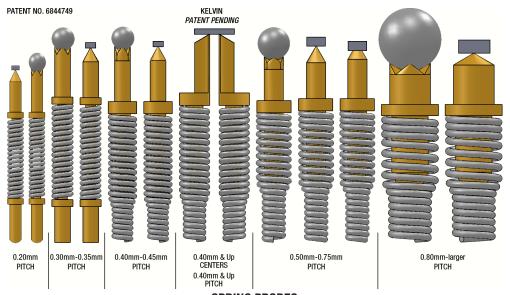






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ALL DIMENSIONS: INCHES [MILLI-METERS]

ALL TOLERANCES: ±0.005 [0.13] UNLESS OTHERWISE SPECIFIED

CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. NOTE: Aries reserves the right to change product general specifications without notice.

SPRING PROBES



Bristol, PA 19007-6810 USA
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